

IN THE CLAIMS:

Please amend the claims as follows:

Claim 1 (Previously Presented): An embedding resin for embedding an electronic part in an insulating substrate, assuming a color having a base color tone selected from among black, blue, green, red, orange, yellow, and violet, and comprising a thermosetting resin and at least one inorganic filler,

wherein the at least one inorganic filler has a particle size range of about 0.1 μm to 50 μm .

Claim 2 (Cancelled).

Claim 3 (Previously Presented): The embedding resin according to claim 1, wherein the thermosetting resin is at least one species selected from among a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, and a cresol-novolak-type epoxy resin.

Claim 4 (Original): The embedding resin according to claim 3, further comprising at least one coloring agent selected from among carbon black, a phthalocyanine-based pigment, an azo pigment, a quinoline-based pigment, an anthraquinone-based pigment, a triphenylmethane-based pigment, and an inorganic oxide.

Claim 5 (Cancelled).

Claim 6 (Original): The embedding resin according to claim 1, further comprising at least one coloring agent selected from among carbon black, a phthalocyanine-based pigment, an azo pigment, a quinoline-based pigment, an anthraquinone-based pigment, a triphenylmethane-based pigment, and an inorganic oxide.

Claim 7 (Previously Presented): The embedding resin according to claim 1, wherein the thermosetting resin contains a photosensitive resin.

Claim 8 (Previously Presented): The embedding resin according to claim 1, wherein the at least one inorganic filler is selected from among crystalline silica, fused silica, alumina, and silicon nitride.

Claim 9 (Previously Presented): The embedding resin according to claim 1, wherein the at least one inorganic filler is subjected to surface treatment by use of a coupling agent.

Claim 10 (Previously Presented): The embedding resin according to claim 4 wherein the amount of the coloring agent is 0.1-30 mass %.

Claim 11 (Previously Presented): The embedding resin according to claim 6 wherein the amount of the coloring agent is 0.1-30 mass %.

Claims 12-14 (Cancelled).

Claim 15 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

and at least one inorganic filler ~~The embedding resin according to claim 13,~~

wherein the at least one inorganic filler has a particle size range of about 0.1 μm to 50 μm .

Claim 16 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

at least one inorganic filler ~~The embedding resin according to claim 13,~~

wherein the thermosetting resin contains a photosensitive resin.

Claim 17 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

at least one inorganic filler The embedding resin according to claim 13,

wherein the at least one inorganic filler is selected from among crystalline silica, fused silica, alumina, and silicon nitride.

Claim 18 (Currently Amended): An embedding resin for embedding an electronic part in an insulating substrate comprising:

carbon black in an amount of 0.1-1.4 mass %;

a thermosetting resin; and

at least one inorganic filler The embedding resin according to claim 13,

wherein the at least one inorganic filler is subjected to surface treatment by use of a coupling agent.